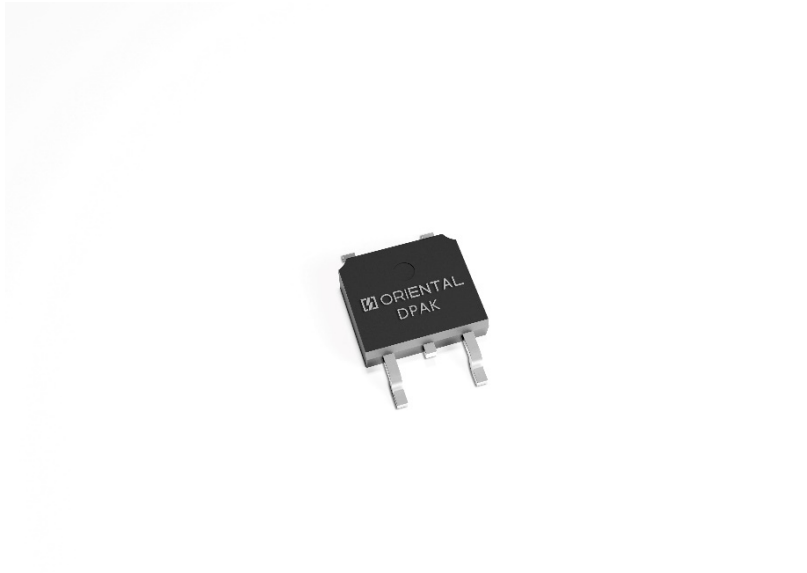




## DPAK Package Type

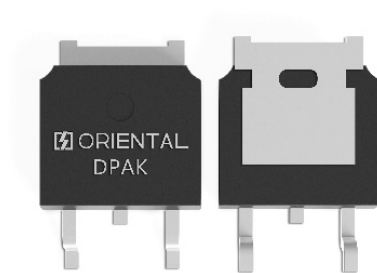
1、D-PAK 是一种塑封贴片封装，常用于功率晶体管、稳压芯片的封装，是目前主流封装之一。

1、D-PAK is a plastic-encapsulated surface-mount package. It is commonly used for packaging power transistors and voltage regulator chips, and ranks among the mainstream package types available today.



2、采用该封装方式的 MOSFET 有 3 个电极，栅极 (G)、漏极 (D)、源极 (S)。

2、MOSFETs adopting this package type feature three electrodes: Gate (G), Drain (D), and Source (S).



3、其中漏极 (D) 的引脚被剪断不用，而是使用背面的散热板作漏极 (D)，直接焊接在 PCB 上，一方面用于输出大电流，一方面通过 PCB 散热；所以 PCB 的 D-PAK 焊盘有三处，漏极 (D) 焊盘较大。其封装规范如下：

3、Among them, the pin of the Drain (D) is cut off and unused; instead, the heat sink on the back



is employed as the Drain (D) and directly soldered onto the PCB. This design serves two purposes: delivering large currents and dissipating heat through the PCB. Therefore, the D-PAK package has three pads on the PCB, with the Drain (D) pad being significantly larger. Its package specifications are as follows:

